

## EHS5



Dual Band  
HSPA



Java  
embedded



Multi Design  
Capability  
(LGA)



RLS Monitoring  
(Jamming Detection)



USB 2.0  
High Speed  
compatible



Advanced  
Temperature  
Management



Embedded  
TCP/IP Stack



eCall /  
ERA GLONASS  
Compliant



FOTA  
configurable &  
free of charge



BIP  
Bearer  
Independent  
Protocol



## 3G

**Cinterion® EHS5 Wireless Module**  
**Highly Efficient 3G in a 2G Footprint**

# Cinterion® EHS5 Wireless Module

## Highly Efficient 3G in a 2G Footprint

The Cinterion EHS5 module represents a milestone in embedded Java machine-to-machine (M2M) communication, offering smart connectivity for industrial applications.

EHS5 delivers highly efficient 3G communication in an ultra-compact footprint. EHS5 is an ideal solution for M2M applications moving to 3G technology with a focus on long-lasting, futureproof and cost efficient M2M applications. Offering a backward and forward compatible footprint, its multi design capability offers seamless migration and unmatched flexibility to choose frequency bands and global roaming whenever needed.

The platform incorporates an improved Java concept using Multi MIDlet Java execution to simultaneously host and run multiple applications and protocols. An extended security concept with the latest TLS/SSL engine provides secure and reliable TCP/IP connectivity while an enriched internal flash file system enables free of charge firmware updates over-the-air (FOTA) when required. Sophisticated sandbox modeling and layered architectures simplify device manage-

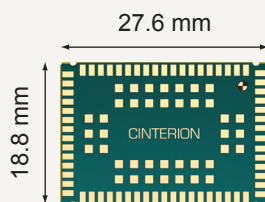
ment (DM) and separate mobile network operator approvals from application code development, allowing simultaneous progress of both phases for a shorter time to market.

Powered by Intel's latest HSPA baseband, the next generation of the award-winning Industrial platform features high speed data communication with 7.2 Mbps (max) in the downlink and 5.76 Mbps (max) in the uplink.

The tiny EHS5 comes in Gemalto M2M's unique LGA (Land Grid Array) package perfectly suited to the manufacturing needs of small, high-volume M2M devices with a focus on reliable and efficient processes. EHS5 supports voice and data communication and best in class low power consumption incorporated with common industrial interfaces such as USB and serial interfaces.

EHS5 is available in two variants: EHS5-US (850/1900 MHz) for North America, and EHS5-E (900/2100 MHz) for the rest of the world.

### Perfect M2M at Minimal Footprint



#### BIP (Bearer Independent Protocol)

BIP secures broadband speed to eUICC (MIM / classic) to enable On-Demand Provision Service (OPS) and Remote Application Management by direct communication between eUICC and network based on internal TCP/IP stack. As a result it enables instant data connectivity on 1st use of a device, as well as a flexible mobile subscription throughout the lifecycle and a reduced number of customer device variants.

#### eCall/ ERA glonass

Equipped with high performance e-call/GLONASS, the EHS5 platform is already prepared to meet the comprehensive requirements of the European eCall and ERA-GLONASS initiatives to bring rapid assistance to motorists involved in a collision.

#### Java™

Java offers easy and fast application development, a broad choice of tools, high code reusability, easy maintenance, a proven security concept, on-device debugging as well as multi-threading programming and program execution.

#### Gemalto M2M Support includes:

- > Personal design-in consulting for hardware and software
- > Extensive RF test capabilities
- > GCF/PTCRB conform pretests to validate approval readiness
- > Regular training workshops



Local engineers, a competent helpdesk, a dedicated team of R&D specialists and an advanced development center are the hallmarks of our leading support offer.

# Cinterion® EHS5 Features

## GENERAL FEATURES

- > 3GPP Rel.7 Compliant Protocol Stack
- > Dual-Band UMTS (WCDMA/FDD)  
EHS5-E: 900 and 2100 MHz  
EHS5-US: 850 and 1900 MHz
- > Dual-Band GSM  
EHS5-E: 900 and 1800 MHz  
EHS5-US: 850 and 1900 MHz
- > SIM Application Toolkit, Class 3, with BIP and RunAT support
- > 3GPP & Russian eCall support
- > Embedded IP stack
- > Control via standardized and extended AT commands (Hayes, TS 27.007 and 27.005)
- > TCP/IP stack access via AT command and transparent TCP services
- > Secure Connection for client IP services
- > Internet Services TCP/UDP server/client, DNS, Ping, FTP client, HTTP client
- > Supply voltage range 3.1 - 4.5 V, highly optimized for minimal power consumption
- > LGA66 soldering mount, MSL4
- > Dimension: 27.6 x 18.8 x 2.3 mm
- > Weight: 2.7 g
- > Operating Temperature: -40 °C to +90 °C

## SPECIFICATIONS

- > HSDPA Cat.8 / HSUPA Cat.6 data rates  
DL: max. 7.2 Mbps, UL: max. 5.76 Mbps
- > EDGE Class 12 data rates  
DL: max. 237 kbps, UL: max. 237 kbps
- > GPRS Class 12 data rates  
DL: max. 85.6 kbps, UL: max. 85.6 kbps
- > CSD data transmission up to 9.6 kbps, V.110, non-transparent
- > SMS text and PDU mode, cell broadcast
- > High quality voice support for handset, headset and hands-free operation
- > Integrated TTY modem
- > Speech codec: FR, HR, EFR and AMR

## SPECIAL FEATURES

- > USB interface supports multiple composite mode and a Linux-/Mac- compliant mode
- > Firmware update via USB and serial interface
- > Real time clock with alarm functionality
- > Multiplexer according 3GPP TS 27.010
- > RLS Monitoring (Jamming detection) in 2G and 3G
- > Informal Network Scan
- > Customer IMEI/SIM-Lock as variant
- > Integrated FOTA, configurable and free of charge

## JAVA OPEN PLATFORM

- > Java™ ME 3.2
- > Secure data transmission with HTTPS/SSL
- > Multi-Threading programming and Multi-Application execution
- > 10 MB RAM and 10 MB Flash File System

## INTERFACES (LGA PADS)

- > Pad for GSM/WCDMA Antenna
- > USB 2.0 HS interface up to 480 Mbps
- > High speed serial modem interface ASC0
- > HSIC HS interface up to 480 Mbps
- > 16 GPIO lines shared with DSR, DTR, DCD (all ASC0), ASC1 (RXD, TXD, RTS, CTS), SPI, Fast-Shutdown, Network-Status-Indication, PWM and Pulse-Counter lines
- > ADC and I2C interface
- > 4-wire high speed serial interface ASC1
- > Digital audio interface
- > UICC and U/SIM card interface 1.8 V / 3 V
- > Lines for Module-On and Reset

## DRIVERS

- > USB, MUX driver for Microsoft® Windows XP™, Vista™ and 7™
- > RIL, USB driver for Microsoft® Windows Embedded-Handheld™ >= 6.x
- > USB, MUX driver for Microsoft® Windows Embedded-Compact™ >= 5.x

## APPROVALS

- > EHS5-E: CE, R&TTE
- > EHS5-US: FCC, PTRCB, UL, IC
- > GCF Listing
- > AT&T and other local approvals and provider certifications
- > EuP, RoHS and REACH compliant

**For more information, please visit**

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